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## **Foxconn, Radiall and Thales Break Ground on Tessalia, a New Semiconductor Assembly and Test Facility in France**

June 1, 2026 - Foxconn, Radiall and Thales celebrated the groundbreaking of their future joint venture, Tessalia Technology SAS, in Le Barp, Nouvelle-Aquitaine, during the Choose France 2026 Summit. The ceremony was attended by Sébastien Martin, French Minister Delegate to the Minister of Industry, Dr. Bob Wei-Ming Chen, President of S Business Group for Hon Hai Technology Group (Foxconn), Pierre Gattaz, Chairman and CEO of Radiall, Patrice Caine, Chairman and CEO of Thales and Alain Rousset, President of the Nouvelle-Aquitaine Region.

The milestone marks a significant step forward in the development of a new European Outsourced Semiconductor Assembly and Testing (OSAT) company dedicated to advanced semiconductor packaging technologies. Tessalia is expected to begin production by the end of 2029 and reach an annual output of more than 50 million System-in-Package (SiP) components by 2033.

**This event comes one year** after French President Emmanuel Macron announced, during the Choose France 2025 Summit, the launch of discussions between Foxconn, Radiall and Thales to establish a strategic semiconductor manufacturing initiative in France.

Located near Bordeaux, Le Barp was selected for its position within a thriving academic and industrial ecosystem, including proximity to the renowned Route des Lasers, advanced cleanroom facilities, and a strong concentration of semiconductor and photonics expertise.

The new company, Tessalia, takes its name from the Latin word *tessella*, the small tiles used to create a mosaic, symbolizing the combination of complementary expertise from its founding partners. Together, Foxconn, the world's largest electronics manufacturing services provider, Radiall, a leading manufacturer of high-performance interconnect solutions, and Thales, a global leader in advanced technologies, will develop, assemble and test advanced semiconductor packaging solutions for sectors including aerospace, telecommunications infrastructure, automotive and medical technologies.

Tessalia will leverage innovative ultra-high-density encapsulation technologies designed to simplify printed circuit board architectures, reduce component size and weight and improve integration capabilities. These advanced packaging technologies are expected to deliver significant gains in performance, manufacturing efficiency and competitiveness for future electronic systems.

The project represents a major investment in Europe's semiconductor ecosystem. Total investment is expected to exceed €250 million by 2033, with the facility projected to employ approximately 800 people at full production capacity. The initiative is also designed to welcome additional industrial partners as the project expands.

Commenting on the significance of the project, Sébastien Martin, French Minister Delegate to the Minister of Industry, said:

*"Today's announcement proves that in just one year, from one Choose France Summit to the next, a strategic vision has become a concrete industrial project. By choosing Le Barp for a facility that strengthens Europe's semiconductor value chain, Foxconn, Thales, and Radiall are demonstrating confidence in France's attractiveness as a technology and industrial hub."*

For Radiall, Tessalia represents both a strategic investment and an important step in strengthening Europe's technological capabilities.

*"This new advanced manufacturing capacity is a key sovereign asset for both the French and European semiconductor industry,"* said Pierre Gattaz, Chairman and CEO of Radiall. *"This project aligns perfectly with Radiall's strategy and will support the development of next-generation interconnect solutions for the most demanding applications."*

The project also supports Foxconn's long-term strategy to expand advanced technology manufacturing through local partnerships.

*"This is not just a factory. It is a strategic platform for advanced manufacturing, semiconductor resilience, and future technologies in Europe,"* said Young Liu, Chairman of Foxconn. *"The project reflects our Build-Operate-Localize strategy, which expands our global technology footprint through trusted partnerships."*

For Thales, Tessalia represents an important step toward strengthening European semiconductor independence and securing critical supply chains.

*"The laying of this first stone demonstrates our shared ambition with Radiall and Foxconn to build an innovative and competitive European player in advanced semiconductor packaging,"* said Patrice Caine, Chairman and CEO of Thales. *"Tessalia is part of a broader effort to strengthen control of the value chain supporting our electronic products and technologies."*

*Regional leaders also welcomed the project as a catalyst for economic development and industrial growth.*

*"I am delighted to welcome this strategic facility, which is essential to strengthening our sovereignty in the electronics sector,"* said Alain Rousset, President of the Nouvelle-Aquitaine Region. *"This project reinforces a regional ecosystem that already supports 20,000 jobs and reflects years of successful efforts to reindustrialize our territory."*

As construction begins, Tessalia is positioned to become a cornerstone of Europe's advanced semiconductor packaging capabilities, helping strengthen industrial resilience, support technological innovation, and contribute to the long-term competitiveness of strategic industries across the continent.